

ABSTRACT OF THE DISCLOSURE

The present invention is for a thermally controlled package for oscillators, particularly
5 evacuated miniature surface acoustical wave oscillators (EMSO) devices. In a preferred
embodiment the surface acoustical wave device is bonded directly to a heated substrate. The
package is evacuated to improve temperature characteristics. A temperature heater, sensor, and
control controller are utilized to maintain the internal package temperature above ambient. In
one embodiment there is an additional substrate layer that house components that are not
10 sensitive to temperature with interconnects electrically connecting the heated substrate and the
additional substrates.

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